

BIOGRAPHY

Advanced Packaging Summit 2026



Name: Minwoo Rhee

Title/ Position: Master and Vice President of Technology

Company: Samsung Electronics

Dr. Minwoo Rhee is a Master and Vice President of Technology at Samsung Electronics, where he leads the development of advanced packaging processes. He earned his B.Eng., M.S., and Ph.D. degrees in Chemical Engineering from Sogang University, Seoul, in 1996, 1998, and 2010, respectively, and received a Master's degree in Industrial Systems Engineering & Management from the National University of Singapore (NUS) in 2017.

With over 27 years of extensive R&D experience in microelectronics packaging across both industry and research institutions, Dr. Rhee possesses deep expertise in advanced packaging architecture, processes, materials, numerical modeling, and characterization. From 1999 to 2011, he served as a senior manager in R&D at Amkor Technology and as a principal engineer in the Package R&D group at Fairchild Semiconductor, where he developed high-power inverter modules for automotive applications. From 2011 to 2015, he was the Head of Department at the Institute of Microelectronics (A*STAR), Singapore, leading the advanced packaging group and various industry consortium projects, including Fan-out WLP, MEMS, and 3DIC TSV.

Dr. Rhee has authored or co-authored more than 100 journal and conference papers and holds over 40 patents in the fields of microelectronics and advanced packaging. He currently serves on the Technical Committee for Packaging Technologies at the IEEE ECTC (Electronic Components and Technology Conference) and is the Co-Chair of the Advanced Packaging Technical Committee at the IEEE EPTC (Electronic Packaging Technology Conference).